ON Semiconductor

Product Bulletin

Document # : PB21098X
Issue Date: 30 October 2015

Title of Change:	Backside Laminate for NB3RL02FCT2G, WLCSP-8 Package
Effective date:	30 October 2015
Contact information:	Contact your local ON Semiconductor Sales Office or <jonathan.bass@onsemi.com>
Type of notification:	ON Semiconductor will consider this change accepted.
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other ________________

Change Sub-Category(s):

☐ Manufacturing Site Change/Addition
☒ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☒ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _________________________

Sites Affected:

☐ All site(s) ☐ not applicable ☐ ON Semiconductor site(s) : ☒ External Foundry/Subcon site(s)
Flip Chip US

Description and Purpose:

Adding backside wafer laminate to provide additional die protection and enhance marking quality for WLCSP-8 bumped die.

Old
No Backside
Laminate

New
With Backside
Laminate

List of affected Standard Parts:

NB3RL02FCT2G